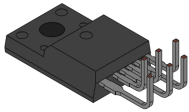


MECHANICAL CASE OUTLINE

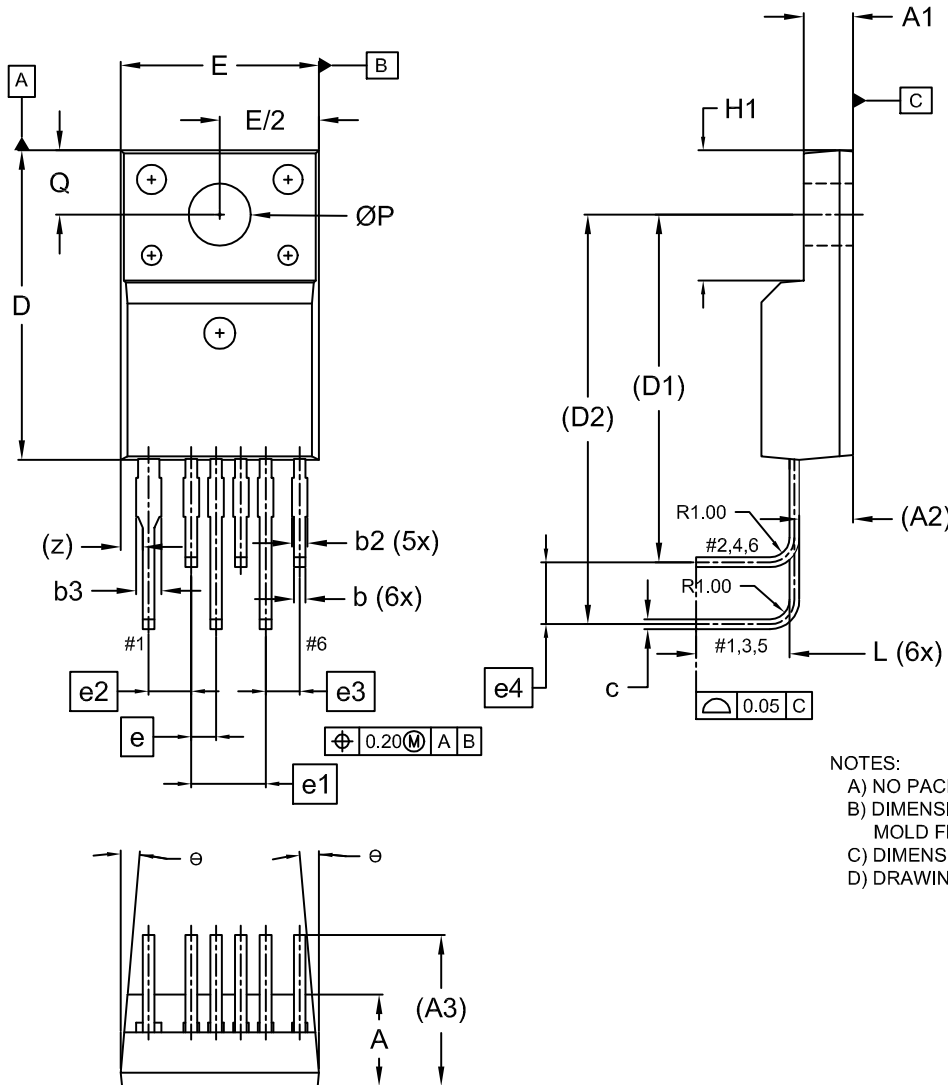
PACKAGE DIMENSIONS

ON Semiconductor®



TO-220-6LD LF
CASE 340BN
ISSUE A

DATE 22 JUL 2021



DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	4.40	4.60	4.80
A1	2.34	2.54	2.74
A2	2.46	2.76	3.06
A3	7.76 REF		
b	0.55	0.60	0.65
b2	0.75	0.80	0.85
b3	1.05	1.18	1.30
c	0.46	0.54	0.61
D	15.68	15.88	16.08
D1	17.83 REF		
D2	21.01 REF		
E	9.96	10.16	10.36
E/2	4.98	5.08	5.18
e	1.27 BSC		
e1	3.81 BSC		
e2	2.19 BSC		
e3	1.75 BSC		
e4	3.18 BSC		
H1	6.48	6.68	6.88
L	4.70	4.80	4.90
P	3.08	3.18	3.28
Q	3.20	3.30	3.40
z	1.13 REF		
Ø	-	-	5°

NOTES:

- A) NO PACKAGE STANDARD APPLIES.
- B) DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- C) DIMENSIONS ARE IN MILLIMETERS.
- D) DRAWING FILENAME : MKT-TO220E06REV2

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DESCRIPTION:	TO-220-6LD LF	PAGE 1 OF 1

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